

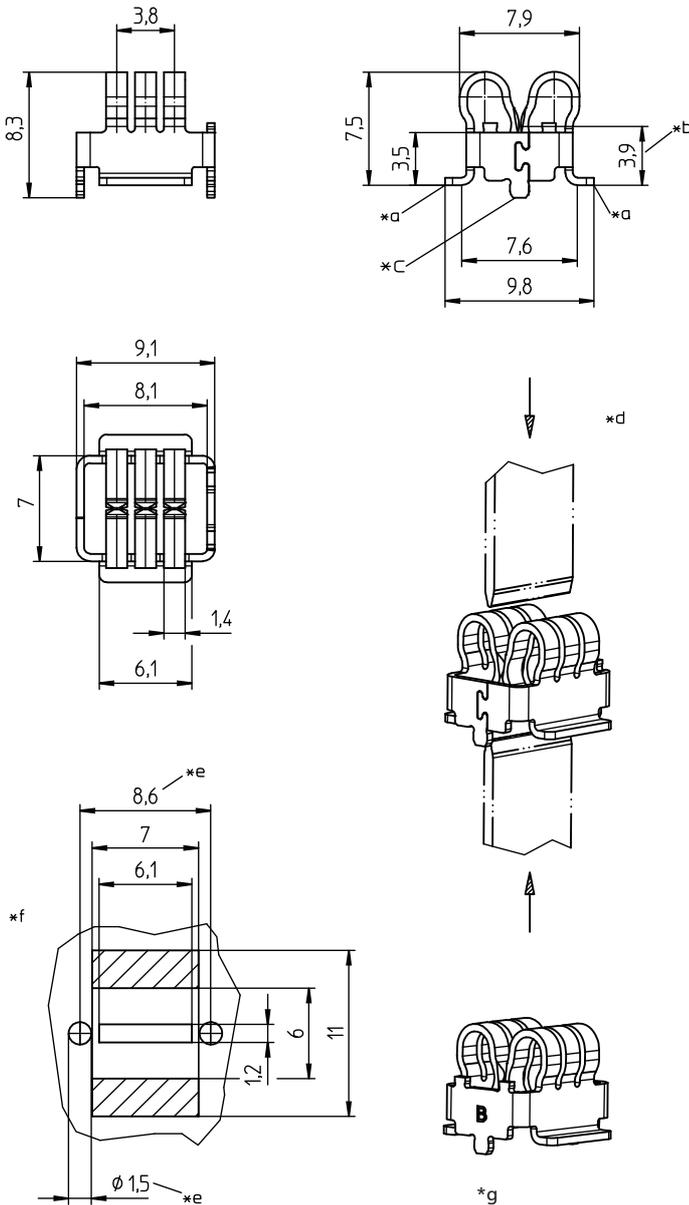
45 4580 03 MP T2,0

High-current contact elements



High-current contact bush with positioning pegs, in surface mount technology (SMT), mateable from top or bottom direction, for tab contacts 1.5–2.0 mm, for printed circuit boards or busbars

45 4580 03 MP T2,0



Environmental conditions

Temperature range -40 °C/+120 °C

Materials

Contact CuCr alloy, tin-plated

Mechanical data

Mating with tab contact 5.3 mm x 1.5–2.0 mm applicable for reflow soldering on printed circuit board applicable for laser welding on a busbar or lead frame

Mating cycles ≤ 5

Insertion force tab contact 1.5 mm 35 N ± 10 N – top or bottom entry tab contact 2.0 mm 35 N ± 10 N – top entry 50 N ± 10 N – bottom entry¹

Withdrawal force 6 N +10/-3 N¹

¹ measured with polished steel test tabs

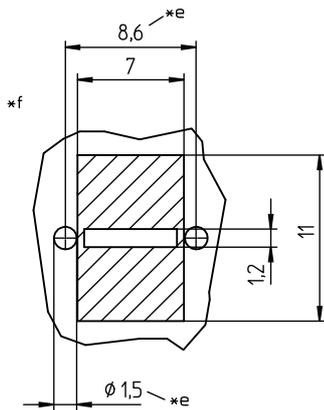
Electrical data (at T_{amb} 20 °C)

Contact resistance < 0.5 mΩ

Rated current ≤ 60 A¹

¹ depending on the connection to the printed circuit board/busbar, installation situation and heat dissipation

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- *a supporting surface for soldering – dimensions per solder pad
min. 7.0 mm x 2.5 mm
- *b height contact point
- *c positioning peg
- *d mateable from top or bottom direction
- *e bore holes for positioning pegs
- *f circuit board layout (example)
- *g marking B for type 4580 03 MP T2,0

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Designation	Pole Number	PU (Pieces)	MDQ (Pieces)
4580 03 MP T2,0 V12VP12	1	350	2100

Packaging:

on reel